# Low-Voltage CMOS Octal D-Type Flip-Flop

## With 5 V-Tolerant Inputs and Outputs (3-State, Non-Inverting)

The MC74LCX374 is a high performance, non–inverting octal D–type flip–flop operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A  $V_{\rm I}$  specification of 5.5 V allows MC74LCX374 inputs to be safely driven from 5 V devices.

The MC74LCX374 consists of 8 edge–triggered flip–flops with individual D–type inputs and 3–state true outputs. The buffered clock and buffered Output Enable  $(\overline{OE})$  are common to all flip–flops. The eight flip–flops will store the state of individual D inputs that meet the setup and hold time requirements on the LOW–to–HIGH Clock (CP) transition. With the  $\overline{OE}$  LOW, the contents of the eight flip–flops are available at the outputs. When the  $\overline{OE}$  is HIGH, the outputs go to the high impedance state. The  $\overline{OE}$  input level does not affect the operation of the flip–flops.

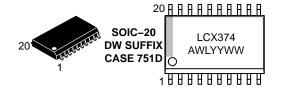
#### **Features**

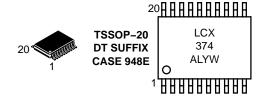
- Designed for 2.3 to 3.6 V V<sub>CC</sub> Operation
- 5 V Tolerant Interface Capability With 5 V TTL Logic
- Supports Live Insertion and Withdrawal
- $I_{OFF}$  Specification Guarantees High Impedance When  $V_{CC} = 0 \text{ V}$
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- $\bullet$  Near Zero Static Supply Current in All Three Logic States (10  $\mu A)$  Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V Machine Model >200 V
- Pb-Free Packages are Available\*

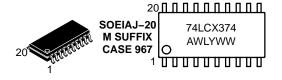


http://onsemi.com

#### MARKING DIAGRAMS







A = Assembly Location

L, WL = Wafer Lot Y, YY = Year W, WW = Work Week

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

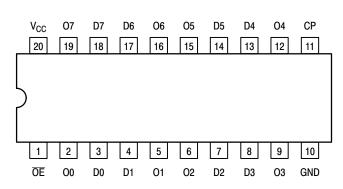


Figure 1. Pinout: 20-Lead (Top View)

#### **PIN NAMES**

Pins	Function
ŌĒ	Output Enable Input
CP	Clock Pulse Input
D0-D7	Data Inputs
00-07	3-State Outputs

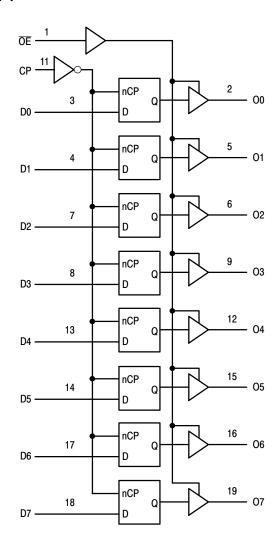


Figure 2. LOGIC DIAGRAM

#### **TRUTH TABLE**

	INPUTS		OUTPUTS	
ŌĒ	СР	Dn	On	OPERATING MODE
L L	<b>↑</b>	l h	L H	Load and Read Register
L	1	Х	NC	Hold and Read Register
Н	1	Х	Z	Hold and Disable Outputs
H H	<b>↑</b>	l h	Z Z	Load Internal Register and Disable Outputs

H = High Voltage Level

h = High Voltage Level One Setup Time Prior to the Low-to-High Clock Transition

L = Low Voltage Level

I = Low Voltage Level One Setup Time Prior to the Low-to-High Clock Transition

NC = No Change, State Prior to Low-to-High Clock Transition X = High or Low Voltage Level and Transitions are Acceptable

Z = High Impedance State

↑ = Low-to-High Transition

1 = Not a Low-to-High Transition; For I<sub>CC</sub> Reasons, DO NOT FLOAT Inputs

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Condition	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	$-0.5 \le V_1 \le +7.0$		V
Vo	DC Output Voltage	$-0.5 \le V_O \le +7.0$	Output in 3-State	V
		$-0.5 \le V_{O} \le V_{CC} + 0.5$	Note 1	V
I <sub>IK</sub>	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA
I <sub>OK</sub>	DC Output Diode Current	-50	V <sub>O</sub> < GND	mA
		+50	V <sub>O</sub> > V <sub>CC</sub>	mA
Io	DC Output Source/Sink Current	±50		mA
Icc	DC Supply Current Per Supply Pin	±100		mA
I <sub>GND</sub>	DC Ground Current Per Ground Pin	±100		mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150		°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

#### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Unit
V <sub>CC</sub>	Supply Voltage Operating Data Retention Only	2.0 1.5	3.3 3.3	3.6 3.6	V
VI	Input Voltage	0		5.5	V
V <sub>O</sub>	Output Voltage (HIGH or LOW State) (3–State)	0 0		V <sub>CC</sub> 5.5	V
I <sub>OH</sub>	HIGH Level Output Current, V <sub>CC</sub> = 3.0 V – 3.6 V			-24	mA
I <sub>OL</sub>	LOW Level Output Current, V <sub>CC</sub> = 3.0 V – 3.6 V			24	mA
I <sub>OH</sub>	HIGH Level Output Current, V <sub>CC</sub> = 2.7 V - 3.0 V			-12	mA
I <sub>OL</sub>	LOW Level Output Current, V <sub>CC</sub> = 2.7 V - 3.0 V			12	mA
T <sub>A</sub>	Operating Free–Air Temperature	-40		+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, $V_{IN}$ from 0.8 V to 2.0 V, $V_{CC}$ = 3.0 V	0		10	ns/V

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74LCX374DWR2	SOIC-20	1000 Tape & Reel
MC74LCX374DR2G	SOIC-20 (Pb-Free)	1000 Tape & Reel
MC74LCX374DTR2	TSSOP-20*	2000 Tape & Reel
MC74LCX374MEL	SOEIAJ-20	2000 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. \*This package is inherently Pb–Free.

#### DC ELECTRICAL CHARACTERISTICS

			$T_A = -40^{\circ}C$ to $+85^{\circ}C$		
Symbol	Characteristic	Condition	Min	Max	Unit
V <sub>IH</sub>	HIGH Level Input Voltage (Note 2)	$2.7 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}$	2.0		V
V <sub>IL</sub>	LOW Level Input Voltage (Note 2)	$2.7 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}$		0.8	V
V <sub>OH</sub>	HIGH Level Output Voltage	$2.7~\text{V} \le \text{V}_{CC} \le 3.6~\text{V};~\text{I}_{OH} = -100~\mu\text{A}$	V <sub>CC</sub> - 0.2		V
		$V_{CC} = 2.7 \text{ V; } I_{OH} = -12 \text{ mA}$	2.2		
		$V_{CC} = 3.0 \text{ V}; I_{OH} = -18 \text{ mA}$	2.4		
		$V_{CC} = 3.0 \text{ V}; I_{OH} = -24 \text{ mA}$	2.2		

<sup>2.</sup> These values of V<sub>I</sub> are used to test DC electrical characteristics only.

<sup>1.</sup> Output in HIGH or LOW State. Io absolute maximum rating must be observed.

#### DC ELECTRICAL CHARACTERISTICS (Continued)

			T <sub>A</sub> = -40°C	c to +85°C	
Symbol	Characteristic	Condition	Min	Max	Unit
V <sub>OL</sub>	LOW Level Output Voltage	$2.7 \text{ V} \le V_{CC} \le 3.6 \text{ V}; I_{OL} = 100 \mu\text{A}$		0.2	V
		V <sub>CC</sub> = 2.7 V; I <sub>OL</sub> = 12 mA		0.4	
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 16 mA		0.4	
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 24 mA		0.55	
II	Input Leakage Current	$2.7 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; 0 \text{ V} \le \text{V}_{I} \le 5.5 \text{ V}$		±5.0	μΑ
I <sub>OZ</sub>	3-State Output Current	$2.7 \le V_{CC} \le 3.6 \text{ V}; 0 \text{ V} \le V_{O} \le 5.5 \text{ V};$ $V_{I} = V_{IH} \text{ or V }_{IL}$		±5.0	μΑ
l <sub>OFF</sub>	Power-Off Leakage Current	$V_{CC} = 0 \text{ V}; V_{I} \text{ or } V_{O} = 5.5 \text{ V}$		10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	$2.7 \le V_{CC} \le 3.6 \text{ V}; V_I = \text{GND or } V_{CC}$		10	μΑ
		$2.7 \le V_{CC} \le 3.6 \text{ V}; 3.6 \le V_{I} \text{ or } V_{O} \le 5.5 \text{ V}$		±10	μΑ
$\Delta I_{CC}$	Increase in I <sub>CC</sub> per Input	$2.7 \le V_{CC} \le 3.6 \text{ V}; V_{IH} = V_{CC} - 0.6 \text{ V}$		500	μА

#### AC CHARACTERISTICS (t\_R = t\_F = 2.5 ns; C\_L = 50 pF; R\_L = 500 $\Omega$ )

				Lin	nits		
				T <sub>A</sub> = -40°0	C to +85°C		
			V <sub>CC</sub> = 3.0	V to 3.6 V	V <sub>CC</sub> =	2.7 V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Unit
f <sub>max</sub>	Clock Pulse Frequency	1	150				MHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay CP to O <sub>n</sub>	1	1.5 1.5	8.5 8.5	1.5 1.5	9.5 9.5	ns
t <sub>PZH</sub> t <sub>PZL</sub>	Output Enable Time to HIGH and LOW Levels	2	1.5 1.5	8.5 8.5	1.5 1.5	9.5 9.5	ns
t <sub>PHZ</sub>	Output Disable Time from HIGH and LOW Levels	2	1.5 1.5	7.5 7.5	1.5 1.5	8.5 8.5	ns
t <sub>s</sub>	Setup Time, HIGH or LOW D <sub>n</sub> to CP	1	2.5		2.5		ns
t <sub>h</sub>	Hold Time, HIGH or LOW D <sub>n</sub> to CP	1	1.5		1.5		ns
t <sub>w</sub>	CP Pulse Width, HIGH or LOW	3	3.3		3.3		ns
t <sub>OSHL</sub>	Output-to-Output Skew (Note 3)			1.0 1.0			ns

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

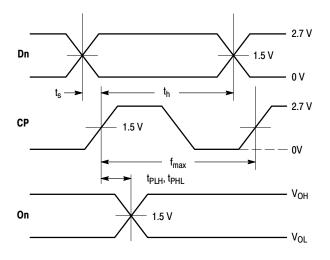
#### **DYNAMIC SWITCHING CHARACTERISTICS**

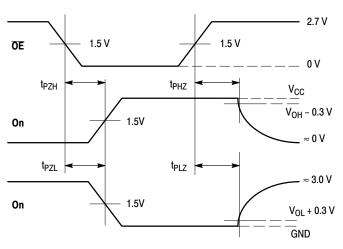
			T,	<sub>A</sub> = +25°	С	
Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V <sub>OLP</sub>	Dynamic LOW Peak Voltage (Note 4)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$		0.8		V
V <sub>OLV</sub>	Dynamic LOW Valley Voltage (Note 4)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$		0.8		V

<sup>4.</sup> Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

#### **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC} = 3.3 \text{ V}, V_{I} = 0 \text{ V or } V_{CC}$	7	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	8	pF
$C_{PD}$	Power Dissipation Capacitance	10 MHz, $V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	25	pF



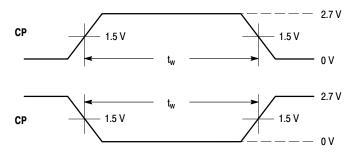


#### WAVEFORM 1 - PROPAGATION DELAYS, SETUP AND HOLD TIMES

 $t_R$  =  $t_F$  = 2.5 ns, 10% to 90%; f = 1 MHz;  $t_W$  = 500 ns

#### WAVEFORM 2 - OUTPUT ENABLE AND DISABLE TIMES

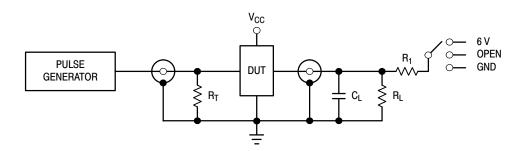
 $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$ 



#### **WAVEFORM 3 - PULSE WIDTH**

 $t_R = t_F = 2.5$  ns (or fast as required) from 10% to 90%; Output requirements:  $V_{OL} \le 0.8 \text{ V}, V_{OH} \ge 2.0 \text{ V}$ 

Figure 3. AC Waveforms



TEST	SWITCH
t <sub>PLH</sub> , t <sub>PHL</sub>	Open
t <sub>PZL</sub> , t <sub>PLZ</sub>	6 V
Open Collector/Drain t <sub>PLH</sub> and t <sub>PHL</sub>	6 V
t <sub>PZH</sub> , t <sub>PHZ</sub>	GND

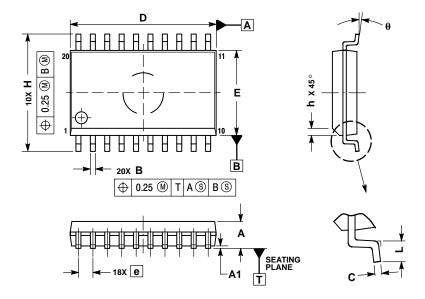
 $C_L$  = 50 pF or equivalent (Includes jig and probe capacitance)  $R_L$  =  $R_1$  = 500  $\Omega$  or equivalent

 $R_T = Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

Figure 4. Test Circuit

#### PACKAGE DIMENSIONS

#### SOIC-20 **DW SUFFIX** CASE 751D-05 ISSUE G



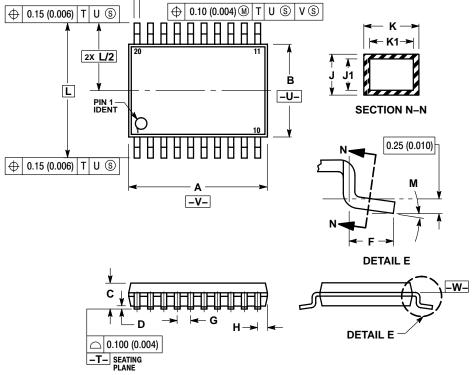
20X **K** REF

#### NOTES:

- DIMENSIONS ARE IN MILLIMETERS.
  INTERPRET DIMENSIONS AND TOLERANCES
  PER ASME Y14.5M, 1994.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
- PROTRUSION: MAXIMUM MOLD PROTRUSION 0.15 PER SIDE. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS				
DIM	MIN	MAX			
Α	2.35	2.65			
A1	0.10	0.25			
В	0.35	0.49			
C	0.23	0.32			
D	12.65	12.95			
E	7.40	7.60			
е	1.27	BSC			
Н	10.05	10.55			
h	0.25	0.75			
L	0.50	0.90			
A	0 0	7 °			

#### TSSOP-20 **DT SUFFIX** CASE 948E-02 **ISSUE B**



#### NOTES:

- DTES:

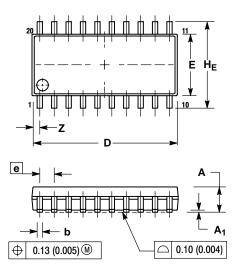
  1. DIMENSIONING AND TOLERANCING
  PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION:
  MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE
  MOLD FLASH, PROTRUSIONS OR GATE
  BURRS. MOLD FLASH OR GATE BURRS
  SHALL NOT EXCEED 0.15 (0.006) PER
  SIDE
- SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION.
  SHALL NOT EXCEED 0.25 (0.010) PER
- SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 DAMBAR FOR THOSING STALL BOOM (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. 3. TERMINAL NUMBERS ARE SHOWN
- FOR REFERENCE ONLY.

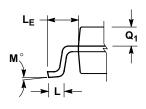
  7. DIMENSION A AND B ARE TO BE
  DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

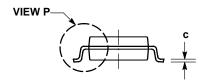
#### **PACKAGE DIMENSIONS**

#### SOEIAJ-20 **M SUFFIX** CASE 967-01 **ISSUE O**





**DETAIL P** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI
  Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
- CONTROLLING DIMENSION. MILLIME I ER.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD
  FLASH OR PROTRUSIONS AND ARE MEASURED
  AT THE PARTING LINE. MOLD FLASH OR
  PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006)
- PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006)
  PER SIDE.
  TERMINAL NUMBERS ARE SHOWN FOR
  REFERENCE ONLY.
  THE LEAD WIDTH DIMENSION (b) DOES NOT
  INCLUDE DAMBAR PROTRUSION. ALLOWABLE
  DAMBAR PROTRUSION SHALL BE 0.08 (0.003)
  TOTAL IN EXCESS OF THE LEAD WIDTH
  DIMENSION AT MAXIMUM MATERIAL CONDITION.
  DAMBAR CANNOT BE LOCATED ON THE LOWER
  RADIUS OR THE FOOT. MINIMUM SPACE
  BETWEEN PROTRUSIONS AND ADJACENT LEAD
  TO BE 0.46 (0.018). TO BE 0.46 ( 0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.18	0.27	0.007	0.011
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
М	0 °	10 °	0 °	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z		0.81		0.032

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